

# CGH55015F

## 15 W, 5500-5800 MHz, GaN HEMT for WiMAX

Cree's CGH55015F is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically for high efficiency, high gain and wide bandwidth capabilities, which makes the CGH55015F ideal for 5.5-5.8 GHz WiMAX and BWA amplifier applications. The transistor is supplied in a ceramic/metal flange package. Based on appropriate external match adjustment, the CGH55015F is suitable for 4.9 - 5.5 GHz applications as well.



Package Type: 440166  
PN: CGH55015F

### Typical Performance 5.5-5.8GHz ( $T_c = 25^\circ\text{C}$ )

Parameter	5.50 GHz	5.65 GHz	5.80 GHz	Units
Small Signal Gain	10.7	11.0	10.7	dB
EVM at $P_{AVE} = 23$ dBm	1.9	1.8	2.0	%
EVM at $P_{AVE} = 33$ dBm	1.5	1.5	1.7	%
Drain Efficiency at $P_{AVE} = 33$ dBm	25	25	25	%
Input Return Loss	11.5	14.5	10.5	dB

**Note:**

Measured in the CGH55015F-TB amplifier circuit, under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, 5 ms Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

### Features



- 5.5 - 5.8 GHz Operation
- 15 W Peak Power Capability
- >10.5 dB Small Signal Gain
- 2 W  $P_{AVE} < 2.0$  % EVM
- 25 % Efficiency at 2 W Average Power
- Designed for WiMAX Fixed Access 802.16-2004 OFDM Applications
- Designed for Multi-carrier DOCSIS Applications

Large Signal Models Available for SiC & GaN



## Absolute Maximum Ratings (not simultaneous) at 25 °C Case Temperature

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DSS}$	84	Volts
Gate-to-Source Voltage	$V_{GS}$	-10, +2	Volts
Power Dissipation	$P_{DISS}$	7	Watts
Storage Temperature	$T_{STG}$	-55, +150	°C
Operating Junction Temperature	$T_J$	225	°C
Maximum Forward Gate Current	$I_{GMAX}$	4.0	mA
Soldering Temperature <sup>1</sup>	$T_S$	245	°C
Screw Torque	$\tau$	60	in-oz
Thermal Resistance, Junction to Case <sup>2</sup>	$R_{\theta JC}$	8.0	°C/W
Case Operating Temperature <sup>2</sup>	$T_C$	-40, +105	°C

Note:

<sup>1</sup> Refer to the Application Note on soldering at [www.cree.com/products/wireless\\_appnotes.asp](http://www.cree.com/products/wireless_appnotes.asp)

<sup>2</sup> Measured for the CGH55015F at  $P_{DISS} = 7W$ .

## Electrical Characteristics ( $T_C = 25^\circ C$ )

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
<b>DC Characteristics<sup>1</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	-3.8	-3.3	-2.3	VDC	$V_{DS} = 10 V, I_D = 3.6 mA$
Gate Quiescent Voltage	$V_{GS(Q)}$	-	-3.0	-	VDC	$V_{DS} = 28 V, I_D = 115 mA$
Saturated Drain Current	$I_{DS}$	2.9	3.5	-	A	$V_{DS} = 6.0 V, V_{GS} = 2.0 V$
Drain-Source Breakdown Voltage	$V_{BR}$	84	100	-	VDC	$V_{GS} = -8 V, I_D = 3.6 mA$
<b>RF Characteristics<sup>2,3</sup> (<math>T_C = 25^\circ C, F_0 = 5.65 GHz</math> unless otherwise noted)</b>						
Small Signal Gain	$G_{SS}$	8.5	11.0	-	dB	$V_{DD} = 28 V, I_{DQ} = 115 mA$
Drain Efficiency <sup>4</sup>	$\eta$	20.6	25	-	%	$V_{DD} = 28 V, I_{DQ} = 115 mA, P_{AVE} = 2.0 W$
Back-Off Error Vector Magnitude	$EVM_1$	-	2.5	-	%	$V_{DD} = 28 V, I_{DQ} = 115 mA, P_{AVE} = 23 dBm$
Error Vector Magnitude	$EVM_2$	-	2.0	-	%	$V_{DD} = 28 V, I_{DQ} = 115 mA, P_{AVE} = 2.0 W$
Output Mismatch Stress	VSWR	-	10 : 1	-	$\Psi$	No damage at all phase angles, $V_{DD} = 28 V, I_{DQ} = 115 mA, P_{AVE} = 2.0 W$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{GS}$	-	5.00	-	pF	$V_{DS} = 28 V, V_{gs} = -8 V, f = 1 MHz$
Output Capacitance	$C_{DS}$	-	1.32	-	pF	$V_{DS} = 28 V, V_{gs} = -8 V, f = 1 MHz$
Feedback Capacitance	$C_{GD}$	-	0.43	-	pF	$V_{DS} = 28 V, V_{gs} = -8 V, f = 1 MHz$

Notes:

<sup>1</sup> Measured on wafer prior to packaging.

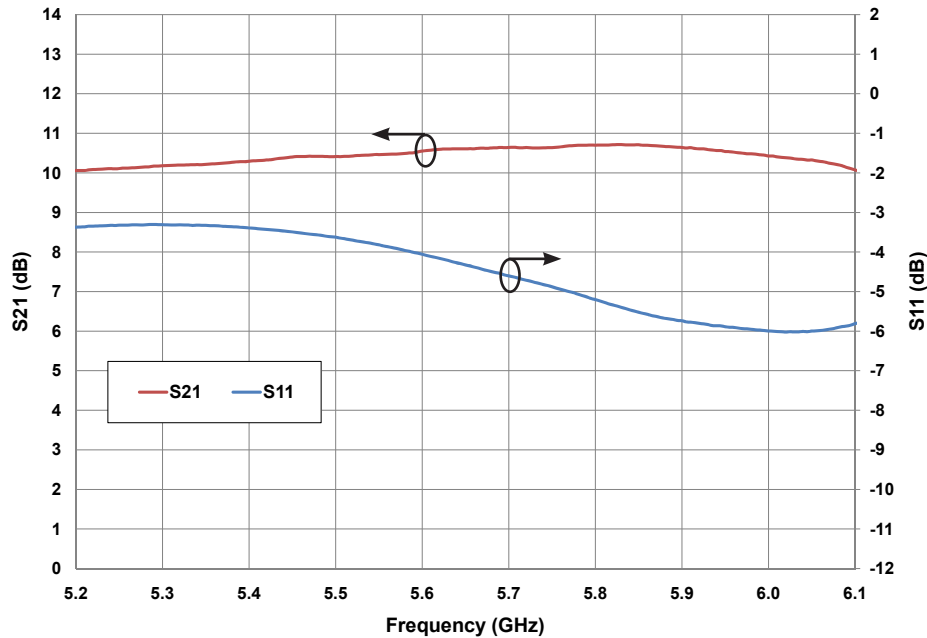
<sup>2</sup> Measured in the CGH55015F-TB test fixture.

<sup>3</sup> Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, 5 ms Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

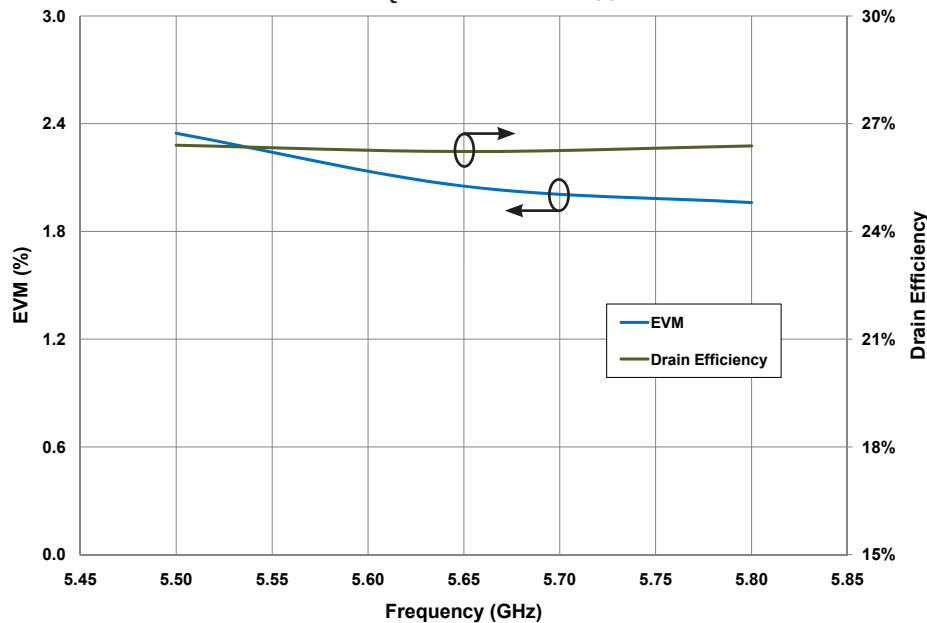
<sup>4</sup> Drain Efficiency =  $P_{OUT} / P_{DC}$ .

## Typical WiMAX Performance

**Small Signal S-Parameters vs Frequency of  
CGH55015F in the CGH55015-TB**  
 $V_{DD} = 28\text{ V}, I_{DQ} = 115\text{ mA}$



**EVM and Efficiency of CGH55015 vs. Frequency  
in the CGH55015-TB**  
 $V_{DD} = 28\text{ V}, I_{DQ} = 115\text{ mA}, P_{OUT} = 2.5\text{ W}$

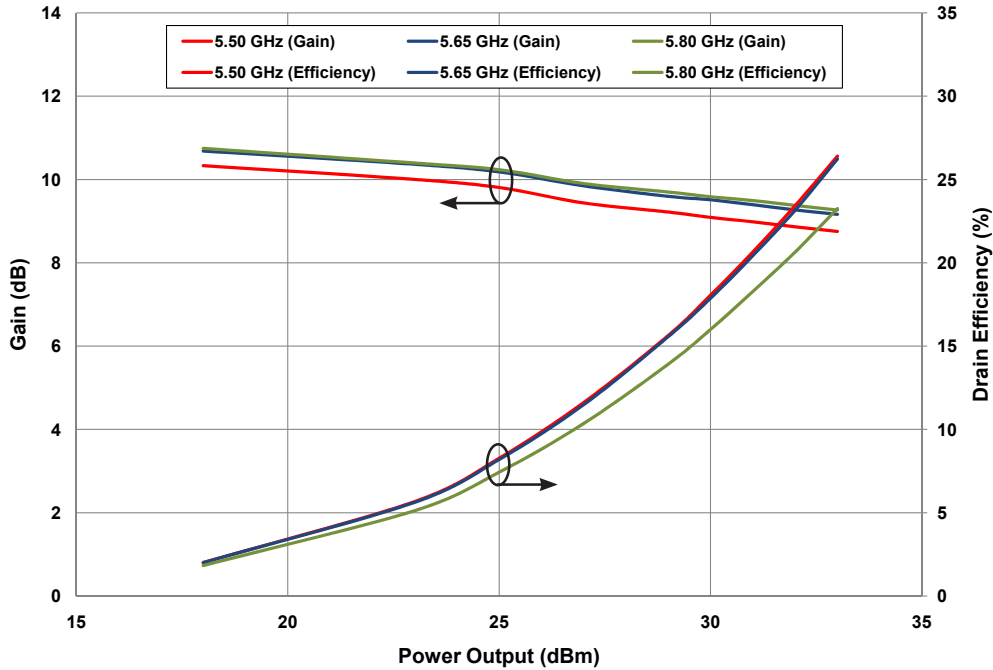


Note:

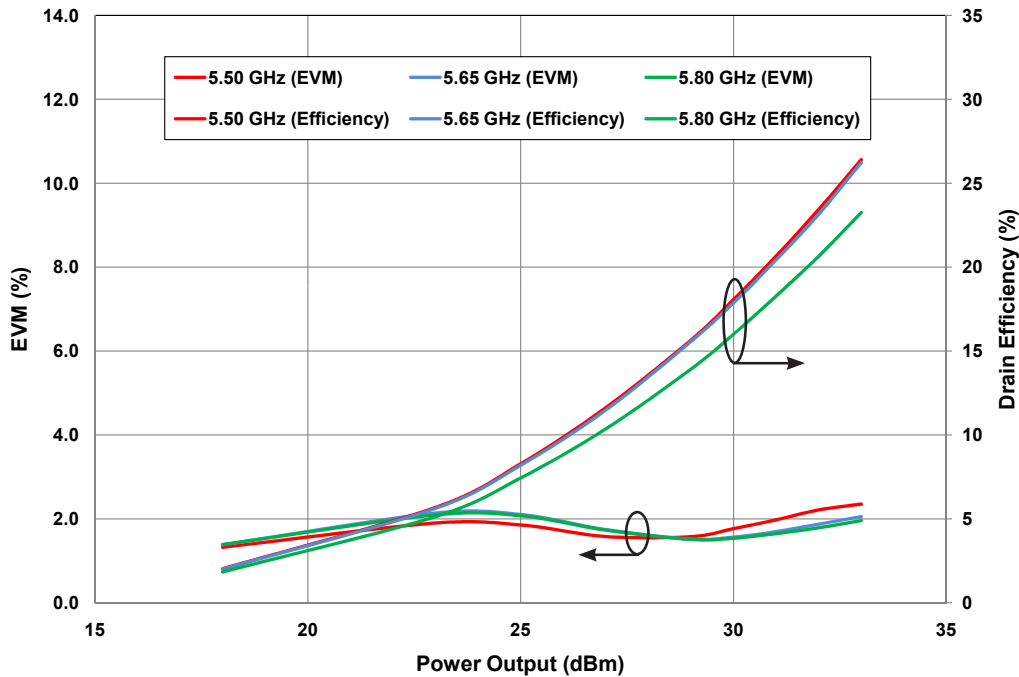
Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

## Typical WiMAX Performance

**Drain Efficiency and Gain vs Power Output of the CGH55015F in the CGH55015-TB**  
 $V_{DD} = 28\text{ V}$ ,  $I_{DQ} = 115\text{ mA}$ , 802.16-2004 OFDM, PAR = 9.8 dB



**Typical EVM and Drain Efficiency vs Output Power of CGH55015F in the CGH55015-TB at 5.50 GHz, 5.65 GHz, 5.80 GHz, 802.16-2004 OFDM, PAR=9.8 dB**



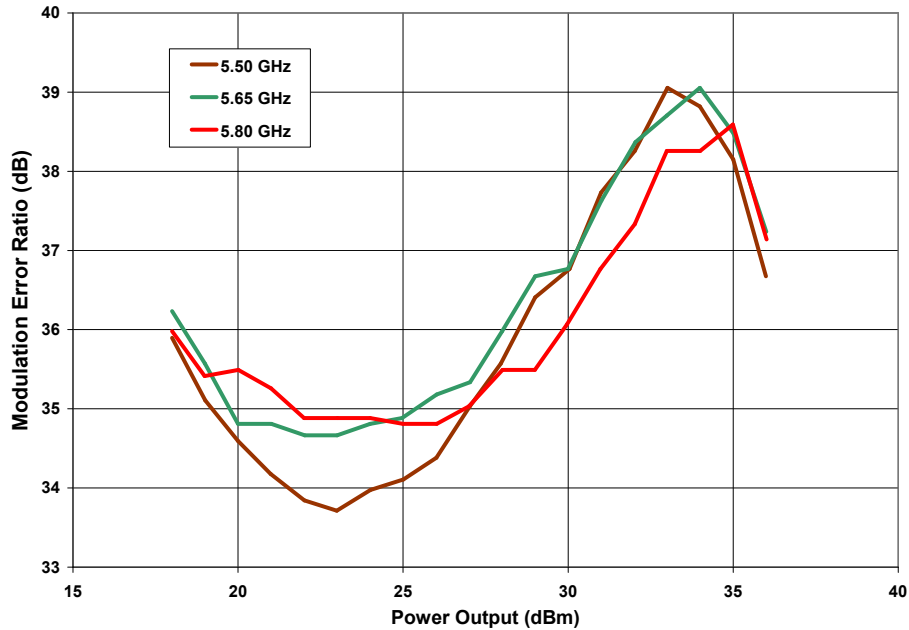
Note:

Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.



## Typical DOCSIS Performance

**DOCSIS Modulation Error Ratio vs Power Output of CGH55015F**

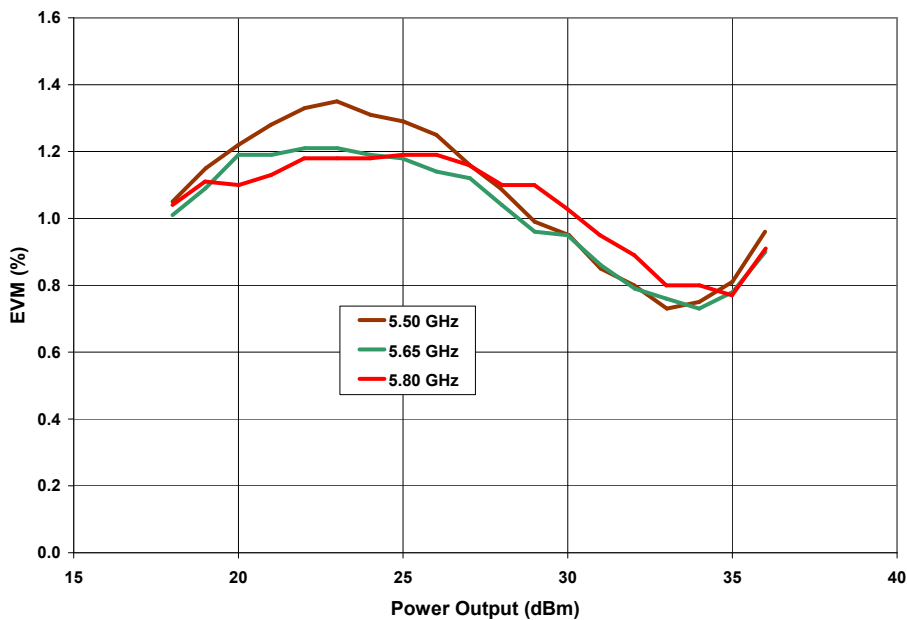


Note:

MER is the metric of choice for cable systems and can be related to EVM by the following equation:  

$$EVM(\%) = 100 \times 10^{-((MER_{dB} + MTA_{dB})/20)}$$
 MTA is the "maximum-to-average constellation power ratio" which varies with the modulation type: MTA = 0 for BPSK and QPSK; 2.55 for 16QAM and 8QAM-DS; 3.68 for 64QAM and 32QAM-DS; 4.23 for 256QAM and 128QAM-DS

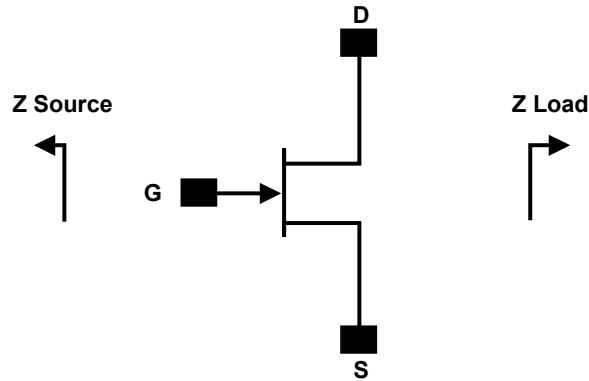
**DOCSIS EVM vs Power Output of CGH55015F in Broadband Amplifier Circuit**



Note:

Under DOCSIS, 6.0 MHz Channel BW, 64 QAM, PN23, Filter Alpha 0.18, PAR = 6.7dB.

## Source and Load Impedances



Frequency (MHz)	Z Source	Z Load
5500	34.4 - j0.8	20 - j5.3
5650	43.3 - j4.8	22.5 - j5.7
5800	49.8 - j14.3	24.9 - j7.1

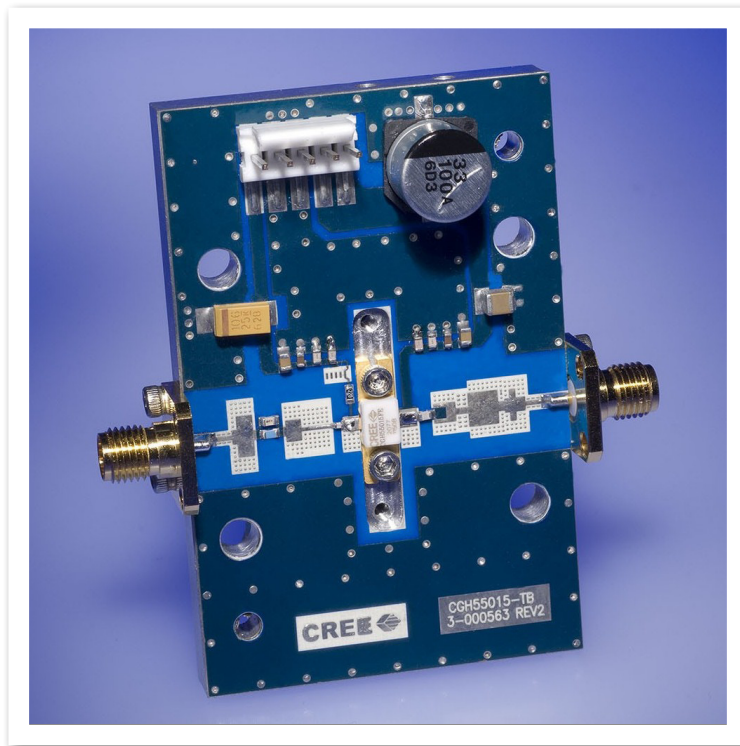
Note 1.  $V_{DD} = 28V$ ,  $I_{DQ} = 115\text{ mA}$  in the 440166 package.

Note 2. Impedances are extracted from the CGH55015-TB demonstration amplifier and are not source and load pull data derived from the transistor.

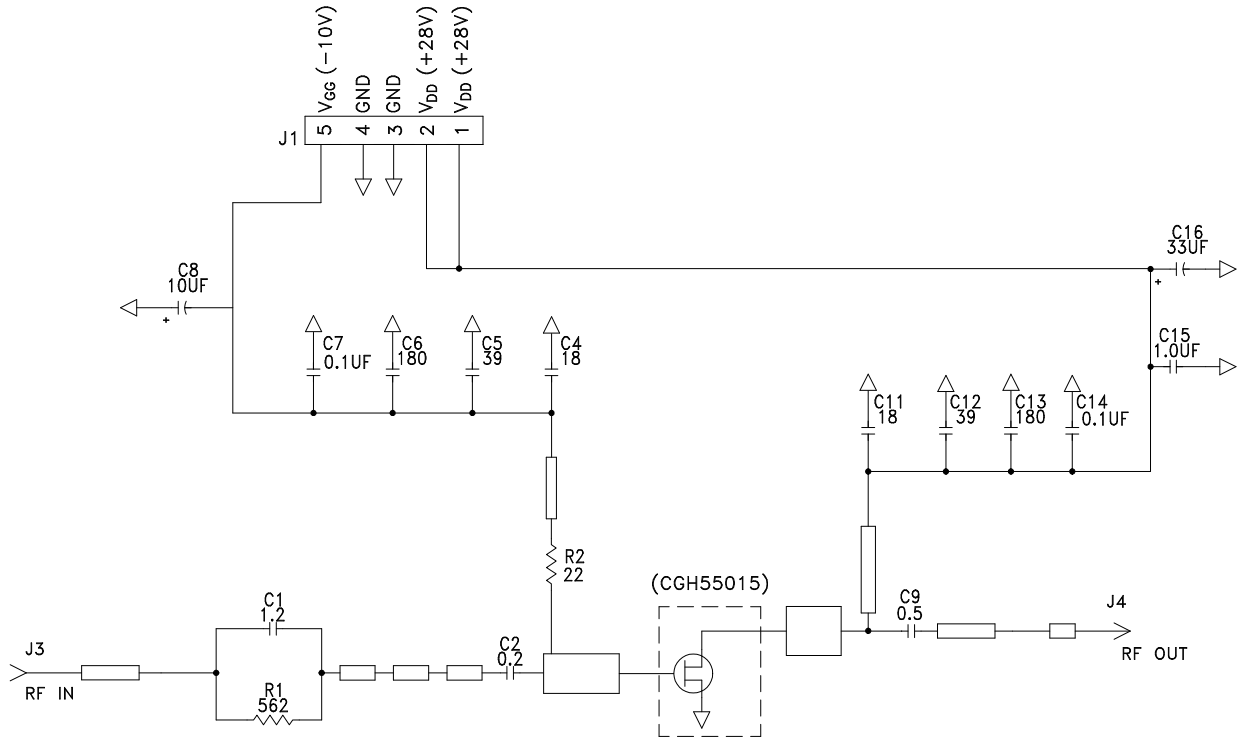
## CGH55015-TB Demonstration Amplifier Circuit Bill of Materials

Designator	Description	Qty
C1	CAP, 1.2pF, +/-0.1 pF, 0603, ATC 600S	1
C2	CAP, 0.2pF, +/-0.05 pF, 0402, ATC 600L	1
C9	CAP, 0.5pF, +/-0.05pF, 0603, ATC 600S	1
C4,C11	CAP, 18pF, +/-5%, 0603, ATC 600S	2
C5,C12	CAP, 39pF +/-5%, 0603, ATC 600S	2
C6,C13	CAP, CER, 180pF, 50V, +/-5%, COG, 0603	2
C7,C14	CAP, CER, 0.1UF, 50V, +/-10%, X7R, 0805	2
C8	CAP, 10UF, 16V, SMT, TANTALUM	1
C15	CAP, 1.0UF ±10%, 100V, 1210, X7R	1
C16	CAP, 33UF, 100V, ELECT, FK, SMD	1
R1	RES, 1/16W, 0603, 1%, 562 OHMS	1
R2	RES, 1/16W, 0603, 1%, 22 OHMS	1
J1	HEADER RT> PLZ .1 CEN LK 5 POS	1
J3,J4	CONN, SMA, FLANGE	2
-	PCB, RO4350B, Er = 3.48, h = 20 mil	1
-	CGH55015	1

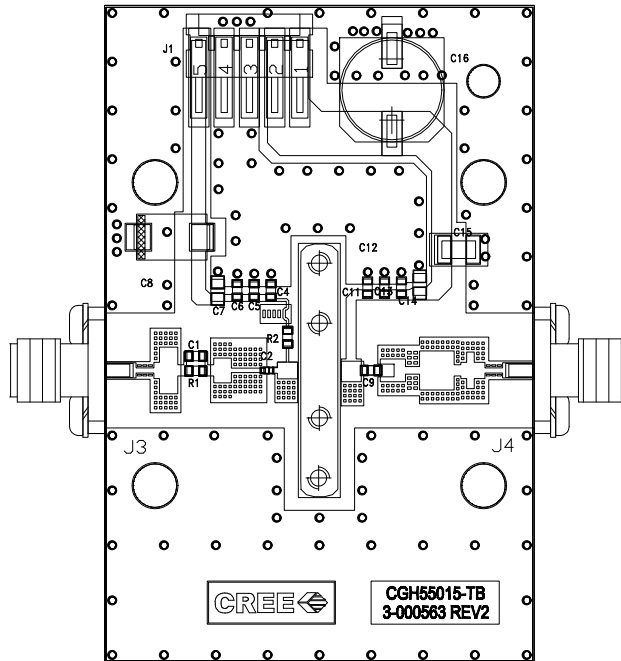
## CGH55015F-TB Demonstration Amplifier Circuit



## CGH55015-TB Demonstration Amplifier Circuit Schematic



## CGH55015-TB Demonstration Amplifier Circuit Outline



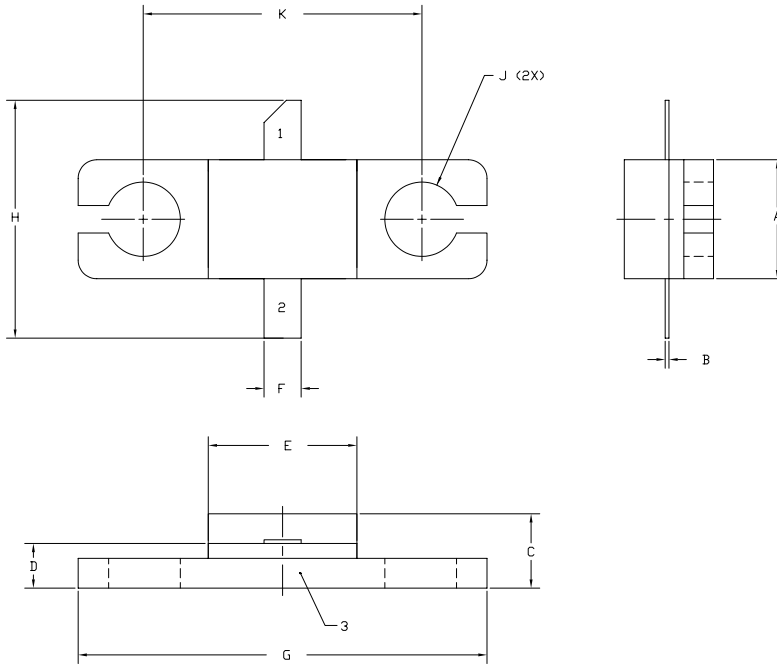


**Typical Package S-Parameters for CGH55015**  
**(Small Signal,  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 115\text{ mA}$ , angle in degrees)**

Frequency	Mag S11	Ang S11	Mag S21	Ang S21	Mag S12	Ang S12	Mag S22	Ang S22
500 MHz	0.894	-133.87	17.74	104.03	0.031	17.114	0.382	-111.59
600 MHz	0.888	-142.35	15.16	98.47	0.032	12.174	0.369	-119.57
700 MHz	0.885	-148.93	13.20	93.83	0.032	8.163	0.361	-125.68
800 MHz	0.882	-154.22	11.67	89.82	0.033	4.775	0.356	-130.45
900 MHz	0.880	-158.62	10.45	86.23	0.033	1.824	0.354	-134.27
1.0 GHz	0.879	-162.36	9.45	82.96	0.033	-0.809	0.354	-137.39
1.1 GHz	0.878	-165.62	8.63	79.93	0.033	-3.205	0.355	-139.98
1.2 GHz	0.878	-168.50	7.93	77.07	0.033	-5.416	0.357	-142.19
1.3 GHz	0.877	-171.11	7.33	74.36	0.033	-7.483	0.360	-144.09
1.4 GHz	0.877	-173.49	6.82	71.75	0.033	-9.431	0.364	-145.77
1.5 GHz	0.877	-175.68	6.37	69.24	0.033	-11.282	0.368	-147.28
1.6 GHz	0.877	-177.74	5.98	66.80	0.032	-13.052	0.372	-148.66
1.7 GHz	0.877	-179.67	5.63	64.43	0.032	-14.751	0.377	-149.94
1.8 GHz	0.877	178.49	5.32	62.10	0.032	-16.390	0.382	-151.14
1.9 GHz	0.877	176.74	5.05	59.83	0.032	-17.975	0.387	-152.29
2.0 GHz	0.877	175.05	4.79	57.59	0.032	-19.512	0.392	-153.39
2.1 GHz	0.878	173.41	4.57	55.38	0.032	-21.005	0.397	-154.47
2.2 GHz	0.878	171.83	4.36	53.21	0.031	-22.458	0.403	-155.52
2.3 GHz	0.878	170.28	4.17	51.06	0.031	-23.874	0.408	-156.56
2.4 GHz	0.878	168.76	4.00	48.93	0.031	-25.255	0.414	-157.59
2.5 GHz	0.878	167.27	3.84	46.82	0.031	-26.603	0.420	-158.62
2.6 GHz	0.879	165.80	3.70	44.74	0.030	-27.919	0.425	-159.65
2.7 GHz	0.879	164.35	3.56	42.66	0.030	-29.204	0.431	-160.69
2.8 GHz	0.879	162.91	3.44	40.61	0.030	-30.460	0.436	-161.73
2.9 GHz	0.879	161.47	3.32	38.56	0.030	-31.687	0.442	-162.78
3.0 GHz	0.880	160.05	3.21	36.53	0.029	-32.886	0.447	-163.84
3.2 GHz	0.880	157.21	3.02	32.49	0.029	-35.198	0.458	-165.99
3.4 GHz	0.881	154.37	2.84	28.47	0.028	-37.398	0.468	-168.19
3.6 GHz	0.881	151.51	2.69	24.48	0.028	-39.484	0.477	-170.44
3.8 GHz	0.881	148.61	2.56	20.51	0.027	-41.454	0.486	-172.76
4.0 GHz	0.881	145.67	2.44	16.53	0.026	-43.302	0.495	-175.13
4.2 GHz	0.882	142.68	2.34	12.55	0.026	-45.024	0.503	-177.57
4.4 GHz	0.882	139.62	2.24	8.57	0.025	-46.613	0.510	179.92
4.6 GHz	0.882	136.48	2.16	4.56	0.025	-48.059	0.516	177.34
4.8 GHz	0.882	133.25	2.08	0.53	0.024	-49.355	0.522	174.69
5.0 GHz	0.881	129.93	2.01	-3.54	0.023	-50.491	0.528	171.95
5.2 GHz	0.881	126.51	1.95	-7.65	0.023	-51.458	0.532	169.13
5.4 GHz	0.881	122.97	1.89	-11.80	0.022	-52.249	0.536	166.21
5.6 GHz	0.881	119.31	1.84	-16.02	0.022	-52.858	0.540	163.19
5.8 GHz	0.880	115.52	1.79	-20.29	0.022	-53.284	0.543	160.06
6.0 GHz	0.880	111.59	1.75	-24.65	0.021	-53.533	0.545	156.81

Download this s-parameter file in ".s2p" format at [http://www.cree.com/products/wireless\\_s-parameters.asp](http://www.cree.com/products/wireless_s-parameters.asp)

# Product Dimensions CGH55015F (Package Type — 440166)



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
5. ALL PLATED SURFACES ARE Ni/AU

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.155	0.165	3.94	4.19
B	0.004	0.006	0.10	0.15
C	0.115	0.135	2.92	3.43
D	0.057	0.067	1.45	1.70
E	0.195	0.205	4.95	5.21
F	0.045	0.055	1.14	1.40
G	0.545	0.555	13.84	14.09
H	0.280	0.360	7.87	8.38
J	Ø .100		2.54	
K	0.375		9.53	

- PIN 1. GATE  
 PIN 2. DRAIN  
 PIN 3. SOURCE



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